Miniature Reflective Object Sensor

Features

- Phototransistor Output
- No Contact Surface Sensing
- Miniature Package
- Lead Form Style: Gull Wing
- Two Leadform Options:
 - ◆ Through Hole (QRE1113)
 - SMT Gull Wing (QRE1113GR & QRE1114GR)
- Two Packaging Options:
 - Tube (QRE1113)
 - Tape and Reel (QRE1113GR & QRE1114GR)

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
T _{OPR}	Operating Temperature	-40 to +85	°C
T _{STG}	Storage Temperature	-40 to +90	°C
T _{SOL-I}	Soldering Temperature (Iron) (Notes 2, 3, 4)	240 for 5 s	°C
T _{SOL-F}	Soldering Temperature (Flow) (Notes 3, 4)	260 for 10 s	°C

EMITTER

١ _F	Continuous Forward Current	50	mA
V _R	Reverse Voltage	5	V
I _{FP}	Peak Forward Current (Note 5)	1	Α
PD	Power Dissipation (Note 1)	75	mW

SENSOR

V _{CEO}	Collector-Emitter Voltage	30	V
V _{ECO}	Emitter-Collector Voltage	5	V
۱ _C	Collector Current	20	mA
PD	Power Dissipation (Note 1)	50	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Derate power dissipation linearly 1.00 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6 mm) from housing.
- 5. Pulse conditions: tp = 100 μ s; T = 10 ms.

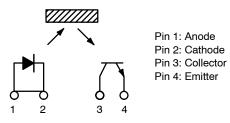
This document, and the information contained herein, is CONFIDENTIAL AND PROPRIETARY and the property of Semiconductor Components Industries, LLC., dba ON Semiconductor. It shall not be used, published, disclosed or disseminated outside of the Company, in whole or in part, without the written permission of ON Semiconductor. Reverse engineering of any or all of the information contained herein is strictly prohibited. © 2020, SCILLC. All Rights Reserved.

© 2020, SCILLO. All Rights Rese



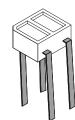
ON Semiconductor®

www.onsemi.com





REFLECTIVE RECTANGULAR SURFACE MOUNT CASE 100CY



REFLECTIVE RECTANGULAR THROUGH HOLE CASE 100AQ

ORDERING INFORMATION

Device	Package	Shipping [†]
QRE1113	Reflective Rectangular (Through Hole)	1600 / Tube
QRE1113GR & QRE1114GR	Reflective Rectangular (Surface Mount)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL/OPTICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
INPUT DIO	DE						
V _F	Forward Voltage	I _F = 20 mA			1.2	1.6	V
I _R	Reverse Leakage Current	V _R = 5 V				10	μA
λ_{PE}	Peak Emission Wavelength	I _F = 20 mA			940		nm
	RANSISTOR						
Ι _D	Collector-Emitter Dark Current	I _F = 0 mA, V _{CE} = 20 V				100	nA
COUPLED							
I _{C(ON)}	On-State Collector Current	I _F = 20 mA, V _{CE} = 5 V (Note 6)	QRE1113 & QRE1113GR	0.10	0.90		mA
			QRE1114GR	0.30		0.60	mA
I _{CX}	Cross-Talk Collector Current	I _F = 20 mA, V _{CE} = 5 V (Note 7)				1	μΑ
V _{CE(SAT)}	Saturation Voltage	I _F = 20 mA, I _C = 50 μA (Note 6)			1	0.3	V
tr	Rise Time	V_{CC} = 5 V, $I_{C(ON)}$ = 100 μ A, R_L = 1 k Ω			20		μs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

20

μs

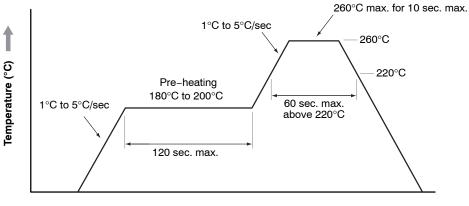
6. Measured using an aluminum alloy mirror at d = 1 mm.

7. No reflective surface at close proximity.

Fall Time

t_f

REFLOW PROFILE



Time (seconds)

Figure 1. Reflow Profile

TYPICAL PERFORMANCE CURVES

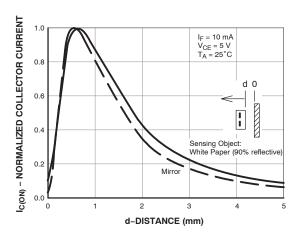
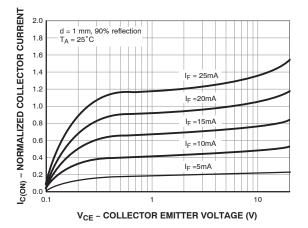


Figure 2. Normalized Collector Current vs. Distance between Device and Reflector





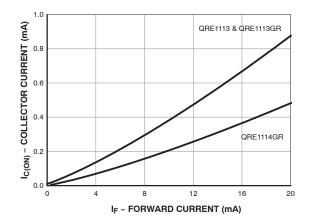


Figure 3. Collector Current vs. Forward Current

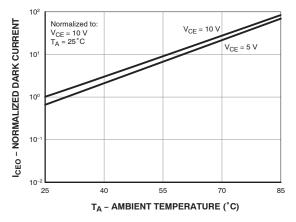


Figure 5. Collector Emitter Dark Current (Normalized) vs. Ambient Temperature

TYPICAL PERFORMANCE CURVES (Continued)

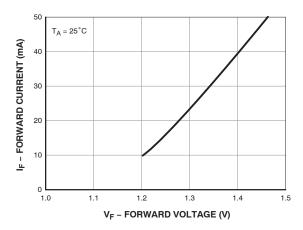


Figure 6. Forward Current vs. Forward Voltage

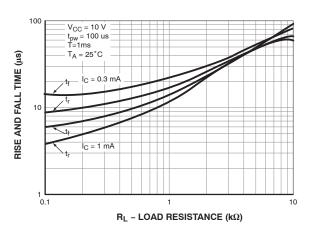


Figure 7. Rise and Fall Time vs. Load Resistance

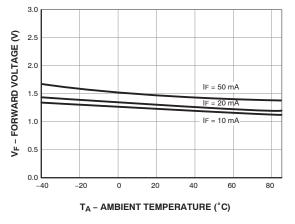


Figure 8. Forward Voltage vs. Ambient Temperature

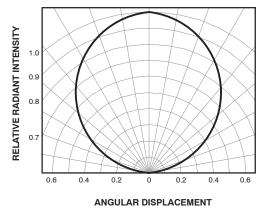
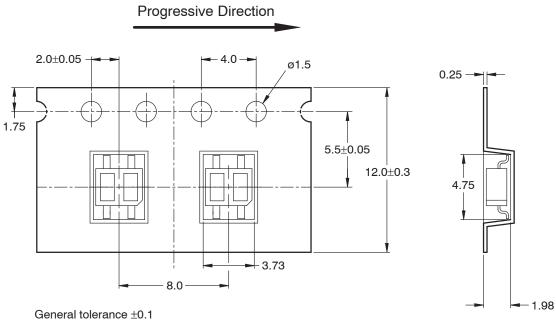


Figure 9. Radiation Diagram

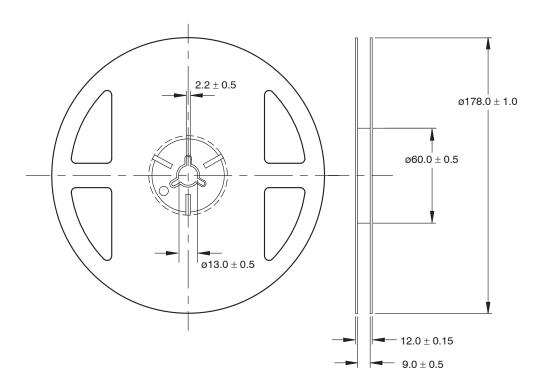
TAPING DIMENSIONS FOR GR OPTION



Dimensions in mm









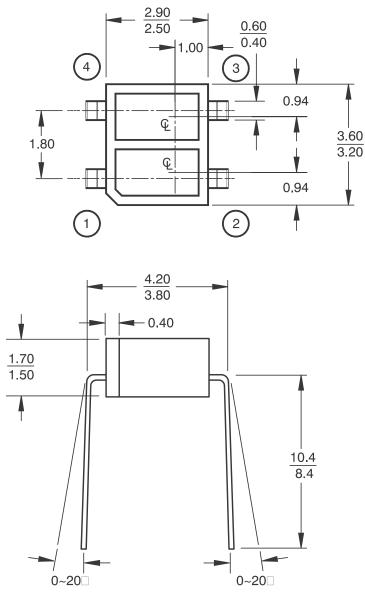
Precautionary Notes

- 1. Refer to application note AND8003/D, "Storage and Handling of Dry Packed Surface Mounted Devices" for details of handling procedure.
- Product soldering terminals are silver plated and oxidization may occur with prolonged exposure to ambient environment. Oxidized terminal
 may have poor solderability performance. Keep unsealed devices in moisture barrier bag sealed with desiccant or in dry cabinet at <5%
 relative humidity.
- Store PCB in sealed moisture barrier bag together with desiccant or store in dry cabinet at <5% relative humidity. Mounted device that has been exposed to ambient environment for long period of time may suffer moisture related damage if PCB is subjected to subsequent high temperature processes.



REFLECTIVE RECTANGULAR THROUGH HOLE CASE 100AQ ISSUE O

DATE 30 SEP 2016



Notes:

1. Dimensions for all drawings are in millimeters.

2. Tolerance of ±0.15mm on all non-nominal dimensions

DOCUMENT NUMBER:	98AON13409G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	REFLECTIVE RECTANGULAR THROUGH HOLE PAGE 1 O		PAGE 1 OF 1		
ON Semiconductor and I are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.					

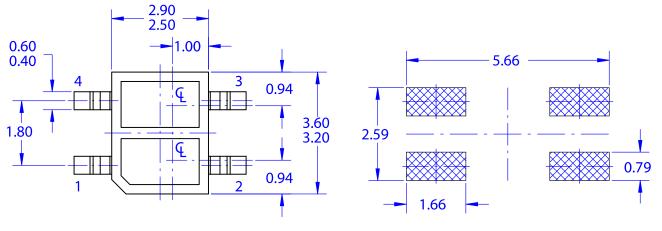
© Semiconductor Components Industries, LLC, 2019



ARUSM-313 / REFLECTIVE RECTANGULAR SURFACE MOUNT CASE 100CY

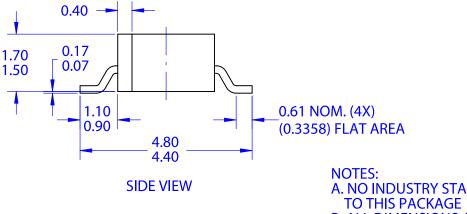
ISSUE O

DATE 31 JAN 2017



TOP VIEW

LAND PATTERN RECOMMENDATION



A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE B. ALL DIMENSIONS ARE IN MILLIMETERS C. TOLERANCE OF ±0.15MM ON ALL NON-NOMINAL DIMENSIONS

DOCUMENT NUMBER:	98AON13407G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	DESCRIPTION: ARUSM-313 / REFLECTIVE RECTANGULAR SURFACE MOUNT PAGE				
ON Semiconductor and ()) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.					

© Semiconductor Components Industries, LLC, 2019

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales